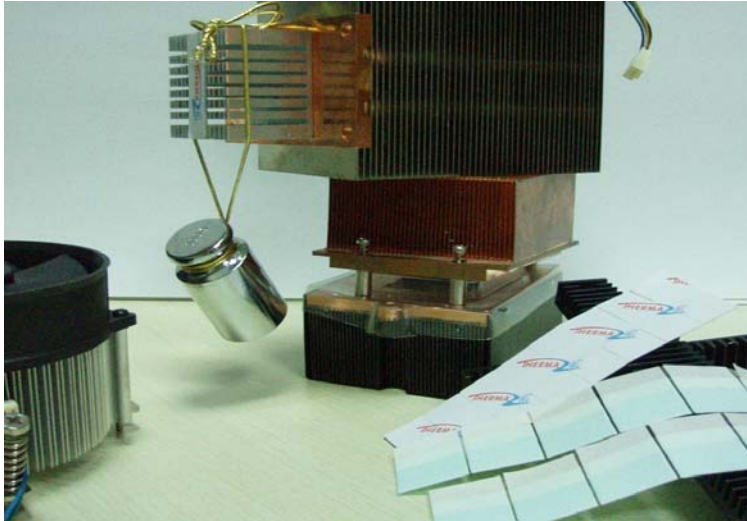


Thermally Conductive Pressure Sensitive Adhesive Tapes

TIA800FG Series thermally conductive sensitive adhesive tapes bond heat sinks to hot components. They adhere components to vertical heat sinks or metal chassis walls in place of clips, screws or other mechanical fasteners, and require no additional thermal compound.



Features and Benefits

- Thermal Conductivity 0.8W/m-K
- High bond strength to a variety of surfaces
- Double sided pressure sensitive adhesive tape
- High performance, thermally conductive acrylic adhesive

Typical Applications Include

- Mount heat sink onto BGA graphic processor or drive processor
- Mount heat spreader onto power converter PCB or onto motor control PCB

Operating Procedure

Pressure(psi)	Temperature(°C)	Time(sec)
10	25	15
30	25	6
10	65	6
30	65	3

Typical Properties of TIA800FG Series

Typical Properties	TIA806FG	TIA812FG	TIA815FG	TIA820FG	Test Method
Color	White				Visual
Reinforcement Carrier	Fiberglass				*****
Thickness (inch/mm)	0.006 / 0.152	0.012 / 0.304	0.015 / 0.381	0.020 / 0.508	ASTM D374
Thickness Tolerance (inch/mm)	±0.001 / ±0.025	±0.0012 / ±0.03	±0.0015 / ±0.038	±0.002 / 0.05	ASTM D374
Voltage Breakdown (Vac)	2000	3000	3500	3500	ASTM D149
Peel Adhesion (g/inch ²)	1,200	1,200	1,200	1,200	JIS K02378
Holding Power (25°C/Days) 1kg/inch ² Creep Adhesion	> 120	> 120	> 120	> 120	JIS K023711
Holding Power (120°C/Hours) 1kg/inch ² Creep Adhesion	> 10	> 10	> 10	> 10	JIS K023711
Recommend Using Pressure (psi)	10	10	10	10	*****
Thermal Conductivity (W/mK)	0.8 W/mK				ASTM D5470